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Part Number: [0736420100](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Press-Fit, Open End, 72 Circuits

Documents:

[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-73670-9999 \(PDF\)](#)

Agency Certification

CSA LR19980
UL E29179

General

Product Family Backplane Connectors
Series [73642](#)
Application Backplane
Comments Standard Press-Fit
Component Type PCB Header
Overview [hdm](#)
Product Name HDM®
Style N/A

Physical

Circuits (Loaded) 72
Circuits (maximum) 72
Color - Resin Black, Natural
Durability (mating cycles max) 250
First Mate / Last Break No
Flammability 94V-0
Guide to Mating Part No
Keying to Mating Part None
Material - Metal Phosphor Bronze
Material - Plating Mating Gold
Material - Plating Termination Gold
Material - Resin High Temperature Thermoplastic
Number of Columns 12
Number of Pairs Open Pin Field
Number of Rows 6
Orientation Vertical
PC Tail Length (in) 0.138 In
PC Tail Length (mm) 3.50 mm
PCB Locator No
PCB Retention Yes
PCB Thickness Recommended (in) 0.098 In
PCB Thickness Recommended (mm) 2.50 mm
Packaging Type Tube
Pitch - Mating Interface (in) 0.079 In
Pitch - Mating Interface (mm) 2.00 mm
Pitch - Term. Interface (in) 0.079 In
Pitch - Term. Interface (mm) 2.00 mm
Plating min: Mating (µin) 30
Plating min: Mating (µm) 0.75
Plating min: Termination (µin) 2
Plating min: Termination (µm) 0.05

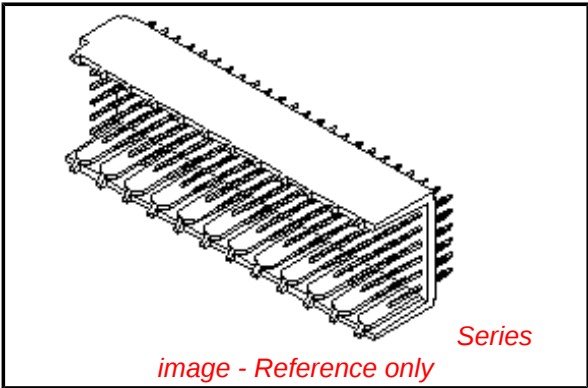


image - Reference only

Series

EU RoHS

**ELV and RoHS
Compliant**
**REACH SVHC
Not Reviewed**
**Halogen-Free
Status
Not Reviewed**

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series
[73642Series](#)

Mates With
[73632](#) HDM PLUS® Board-to-Board
Daughtercard Receptacle. [73780](#) HDM®
Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ
*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global	
Description	Product #
Flat Rock Tooling for	0622013700
Pneumatic Press	
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
Extraction Tool	0621001000

Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Product Specification	PS-73670-9999
Sales Drawing	SDA-73642-****

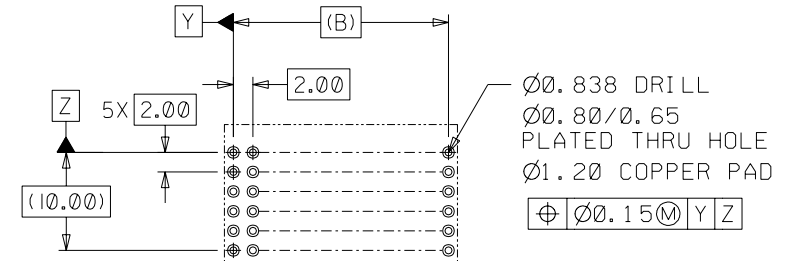
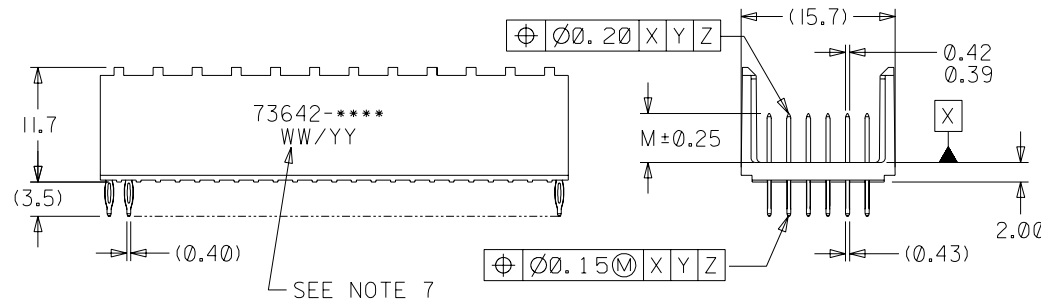
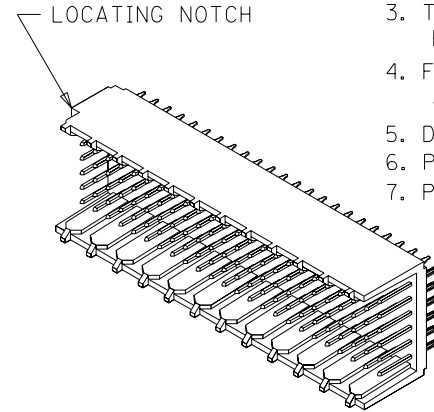
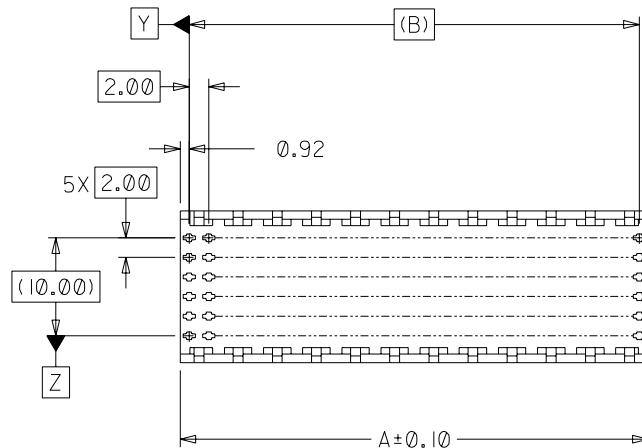
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This document was generated on 05/14/2010

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NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; SELECTIVE TIN/LEAD (Sn/Pb) IN TAIL AREA; NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. DIMENSIONS ARE IN MILLIMETERS.
6. PACKAGE PER PK-70873-0818.
7. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN.

2	C
I	I
SH	REV

I	REVISED ECR UCP2003-2260 THOMAS 03/04/25	F	REVISED ECR UDT1999-0476 BINGHAM 98/12/21	C	REVISED PER ECR *U81357 BINGHAM 97/12/15
H	REVISED ECR UDT2000-0348 BINGHAM 99/10/12	E	REVISED ECR UDT1999-0243 BINGHAM 98/09/29	B	REVISED PER ECR *U70950 BINGHAM 97/02/14
G	REVISED ECR UDT1999-0662 BINGHAM 99/05/18	D	REVISED ECR UDT1998-0240 BINGHAM 98/05/06	A	RELEASED FOR PROD. PER ECR * U70371 BINGHAM 96/12/18
LTR.	REVISIONS	LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH	
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°	
3 PLACE	INCH METRIC
2 PLACE	± N/A ± 0.05
1 PLACE	--- ± 0.10
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
DRWG. BY	JRR
CHK'D. BY	SMR
APP'D. BY	CAB
SCALE	2 : 1

 = 0		 = 0		REVISE ONLY ON CAD SYSTEM		
TITLE						
SALES ASSY, HDM BACKPLANE MODULE, OPEN END OPTION						
 MOLEX INCORPORATED		SHEET NO.		DATE		
LITSE,ILL. 60532 U.S.A.		1 OF 2		96/12/18		
PART NO.		DRWG. NO.				
SEE SHEET 2		SDA-73642-****				
FILE NAME S73642X1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			DIV.	SIZE
					DA	B

	10	9	8	7	6	5	4	3	2	1	73642
F											
E											
D											
C											
B											
A											

MATERIAL NUMBER	NUMBER OF SIGNAL CONTACTS	PLATING	DIM "A"	DIM "B"	DIM "M"
73642-0000	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	5.00
73642-0100	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	5.50
73642-0200	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	6.00
73642-1000	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	5.00
73642-1100	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	5.50
73642-1200	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	6.00
73642-2000	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	5.00
73642-2100	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	5.50
73642-2200	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	6.00
73642-3000	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	5.00
73642-3100	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	5.50
73642-3200	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	6.00

		C	SEE SHEET I
LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH			
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°			
INCH		METRIC	
3 PLACE	± N/A	---	
2 PLACE	± N/A	± 0.05	
1 PLACE	---	± 0.10	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
DRWG. BY	JRR	CHK'D. BY	SMR
APP'D. BY	CAB	SCALE	NO*NE

▽ = 0 ▽ = 0		REVISE ONLY ON CAD SYSTEM	
TITLE SALES ASSY, HDM BACKPLANE MODULE, OPEN END OPTION			
molex MOLEX INCORPORATED LISLE,ILL. 60532 U.S.A.		SHEET NO. 2	DATE 97/12/15
PART NO. SEE CHART		DRWG. NO. SDA-73642-*****	
FILE NAME S73642X2 DGN		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	
		DIV. DA	SIZE B

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<http://moschip.ru/get-element>

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Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

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